Product Change Notification / RMES-02XBET158

Date:

02-Aug-2021

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4407 Final Notice: Qualification of new lead frame design with Double ring Ag on die attach paddle (DAP) surface prep material for selected AT32UC3B0512, AT32UC3C2512C, AT32UC3C2128C, AT32UC3C2256C and AT32UC3C264C device families available in 64L TQFP (10x10x1mm) package using 295x295 mils lead frame paddle size at ANAP assembly site.

Affected CPNs:

RMES-02XBET158_Affected_CPN_08022021.pdf
RMES-02XBET158_Affected_CPN_08022021.csv

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of new lead frame design with Double ring Ag on die attach paddle (DAP) surface prep material for selected AT32UC3B0512, AT32UC3C2512C, AT32UC3C2128C, AT32UC3C2256C and AT32UC3C264C device families available in 64L TQFP (10x10x1mm) package using 295x295 mils lead frame paddle size at ANAP assembly site.

Pre and Post Change Summary:

	Pre Change	**Post Change**

Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)		Amkor Technology Philippine (P1/P2), INC. (ANAP)
Wire material	AuPd		AuPd
Die attach material	3230		3230
Molding compound material	G700L		G700L
Lead frame material	C194		C194
Lead frame Paddle size	295x295 mils	224x240 mils	295x295 mils
Lead frame die attach paddle (DAP) surface prep material	Double Ring Ag	Ring Ag	Double Ring Ag
	See Pre and Post Change attachment for lead frame comparison		

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifyingnew lead frame design with Double ring Ag on die attach paddle (DAP) surface prep material using 295x295 mils lead frame paddle size

Change Implementation Status: In Progress

Estimated First Ship Date:
August 30, 2021(date code: 2136)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2021				
Workweek	32	33	34	35	36
Qual Report Availability	X				
Final PCN Issue Date	X				
Estimated Implementation Date					X

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: August 02, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-02XBET158_Pre and Post Change_Summary.pdf
PCN_RMES-02XBET158_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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